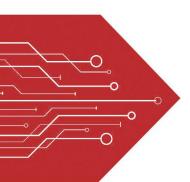
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ESD

TVS

TSS

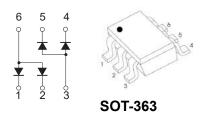
MOV

GDT

PLED

Broduct data sheet





MAKING: KJC



BAW56DW

SWITCHING DIODE

FEATURES

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance

Maximum Ratings @Ta=25℃

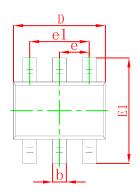
Parameter	Symbol	Limit	Unit
Peak Repetitive Peak Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	75	V
Forward Continuous Current	I _{FM}	300	mA
Average Rectified Output Current	Io	150	mA
Non-Repetitive Peak Forward Surge Current @ t=8.3ms	I _{FSM}	2	А
Power Dissipation	P _D	200	mW
Thermal Resistance From Junction to Ambient	$R_{\theta JA}$	625	°C/W
Operating Junction Temperature	TJ	150	°C
Storage Temperature	T _{STG}	-55~+150	°C

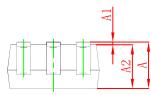
ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

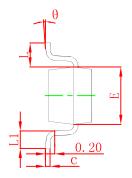
Parameter	Symbol	Test conditions	Min	Max	Unit
Reverse breakdown voltage	V _(BR)	I _R = 2.5μA	75		V
Reverse voltage leakage current	I _R	V _R =75V V _R =20V		2.5 0.025	μΑ
Forward voltage	V _F	$I_F=1mA$ $I_F=10mA$ $I_F=50mA$ $I_F=150mA$		715 855 1000 1250	mV
Capacitance between terminals	Ст	V _R =0, f=1MHz		2	pF
Reveres recovery time	t _{rr}	$I_F = I_R = 10 \text{mA}, I_{rr} = 0.1 \times I_{R_s}$ $R_L = 100 \Omega$		4	ns



SOT-363 Package Outline Dimensions

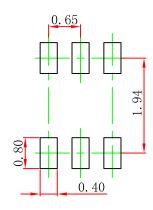






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Syllibol	Min	Max	Min	Max	
Α	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.150	0.350	0.006	0.014	
С	0.100	0.150	0.004	0.006	
D	2.000	2.200	0.079	0.087	
E	1.150	1.350	0.045	0.053	
E1	2.150	2.400	0.085	0.094	
е	0.650 TYP		0.026	STYP	
e1	1.200	1.400	0.047	0.055	
L	0.525 REF		0.021	REF	
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

SOT-363 Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAW56DW	SOT-363	3000



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